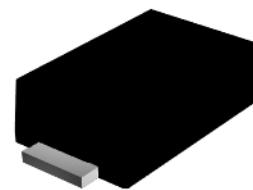


**Features**

- Low profile - typical height of 1.0 mm
- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- AEC-Q101 qualified
- High temperature soldering guaranteed: 260°C /10 seconds
- Halogen-free according to IEC 61249-2-21 definition

Package: eSOP  
(SOD-123FL)RoHS  
COMPLIANT**Applications**

For use in general purpose rectifications in lighting, cellular phones, portable devices, power supplies and other consumer applications.

**Maximum Ratings** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	FH1	FH2	FH3	FH4	FH5	FH6	FH7	Unit
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1.0						A	
Peak Forward Surge Current (8.3 ms single half sine-wave superimposed on rated load)	$I_{FSM}$	30						A	
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150						°C	

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Parameter	Test Conditions	Symbol	FH1	FH2	FH3	FH4	FH5	FH6	FH7	Unit				
Maximum Instantaneous Forward Voltage	1 A	$V_F$	1.3			1.7			A	V				
Maximum DC Reverse Current at rated DC Blocking Voltage	$T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$	$I_R$	5			100			μA					
Maximum Reverse Recovery Time	$I_F=0.5\text{A}, I_R=1.0\text{A}$ $I_{rr}=0.25\text{A}$	$t_{rr}$	50			75			nS					
Typical Thermal Resistance <sup>1)</sup>	Junction to Ambient	$R_{\theta JA}$	66						°C/W					
	Junction to Case	$R_{\theta JC}$	28											
	Junction to Mount	$R_{\theta JM}$	1											

Note:1) The thermal resistance from junction to ambient,case or mount,mounted on P.C.B with 5×5mm copper pads,2OZ,FR4 PCB

## Ratings and Characteristics Curves ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

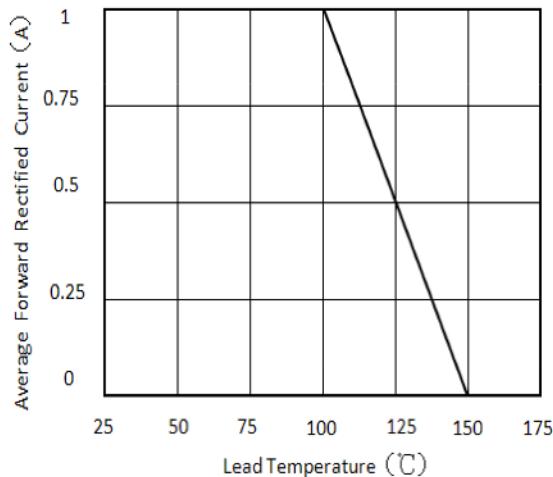


Figure 1. Forward Current Derating Curve

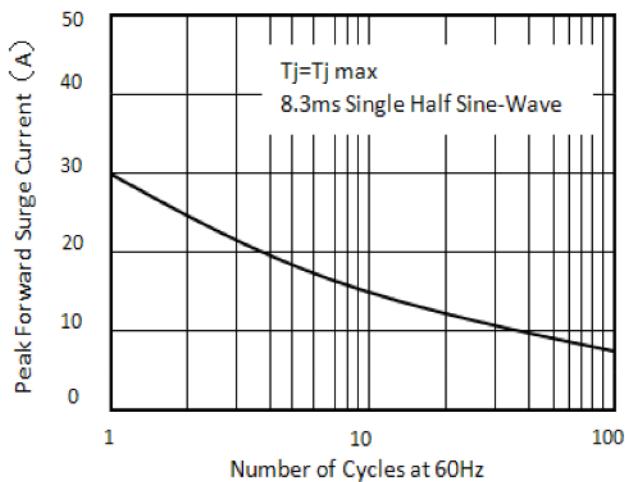


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

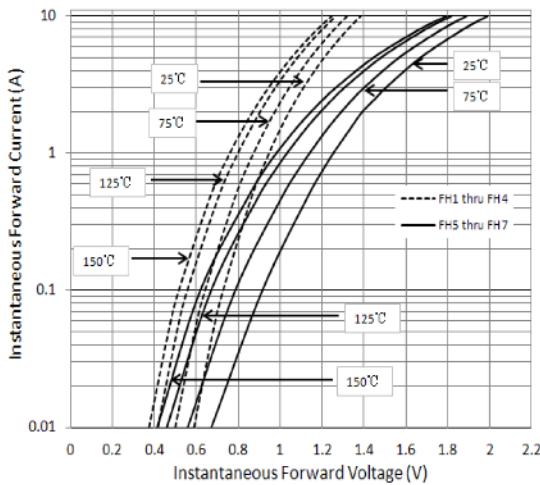


Figure 3. Typical Instantaneous Forward Characteristics

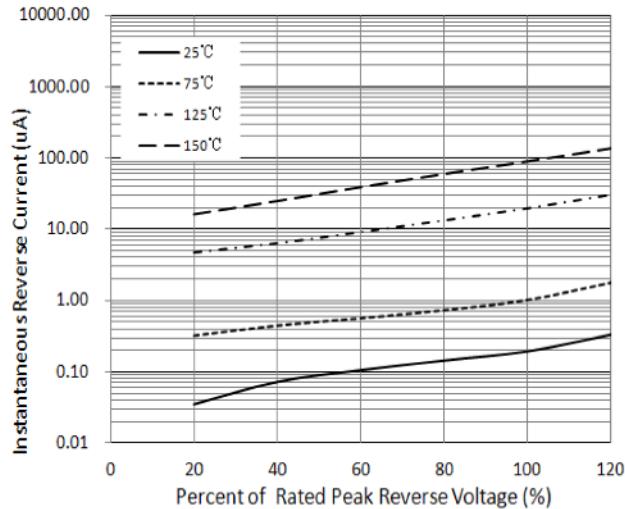
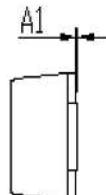
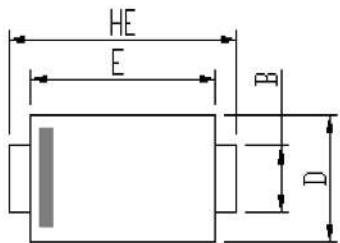
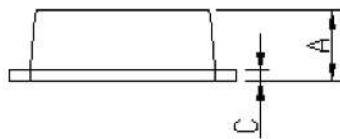


Figure 4. Typical Reverse Characteristics

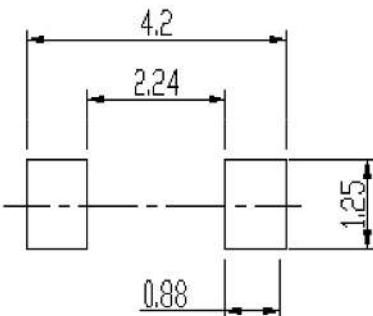
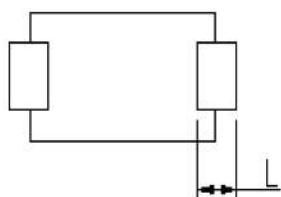
## Package Outline Dimensions

 Package: eSGA  
 (SOD-123FL)


DIM	Unit: mm		Unit: inch	
	MIN	MAX	MIN	MAX
A	0.9	1.08	0.035	0.043
A1	0	0.1	0.000	0.004
B	0.85	1.05	0.033	0.041
C	0.1	0.25	0.004	0.010
D	1.7	2	0.067	0.079
E	2.9	3.1	0.114	0.122
L	0.43	0.83	0.017	0.033
HE	3.5	3.9	0.138	0.154



Soldering footprint



## Packing Information

### Packing Quantities

3000 pcs/Reel, 40 Reels/Box; 8mm Tape, 7" Reel

### Tape & Reel Specifications

